

## Recommended configuration of plated through holes

Due to the high deformation resistance and resilience of **harpress** contacts, they can be easily and repeatedly removed in case of repairs without impairment to their functioning.

**harpress** is extremely versatile and offers a reliable electrical contact, therefore it is especially well suited for applications with these surfaces.

Please contact us for detailed test reports.

In addition to the hot-air-level (HAL) other pcb surfaces are getting more important. Due to their different properties, such as mechanical strength and coefficient of friction we recommend the following configuration of pcb through holes.

<i>Tin-lead plated PCB (HAL) acc. EN 60 352-5</i>	Hole-Ø	1.15±0.025 mm
	Cu	min. 25 µm
	Sn	max. 15 µm
	Plated hole-Ø	0.94-1.09 mm

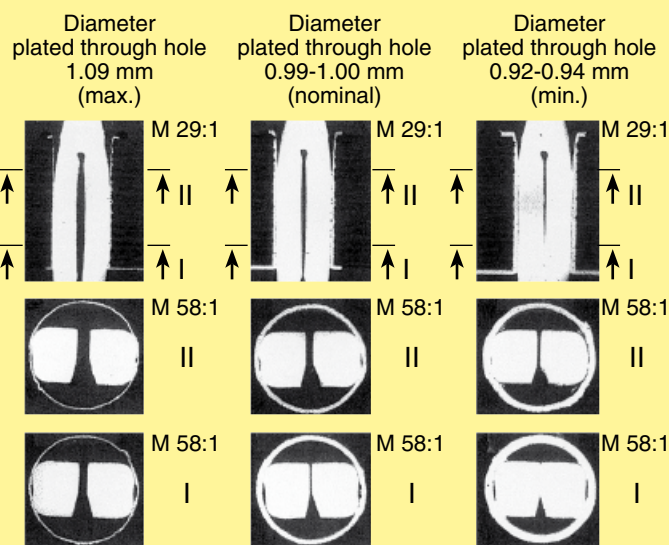
<i>Chemical tin-plated PCB</i>	Hole-Ø	1.15±0.025 mm
	Cu	min. 25 µm
	Sn	min. 0.8 µm
	Plated hole-Ø	1.00-1.10 mm

<i>Au / Ni plated PCB</i>	Hole-Ø	1.15±0.025 mm
	Cu	min. 25 µm
	Ni	3-7 µm
	Au	0.05-0.12 µm
	Plated hole-Ø	1.00-1.10 mm

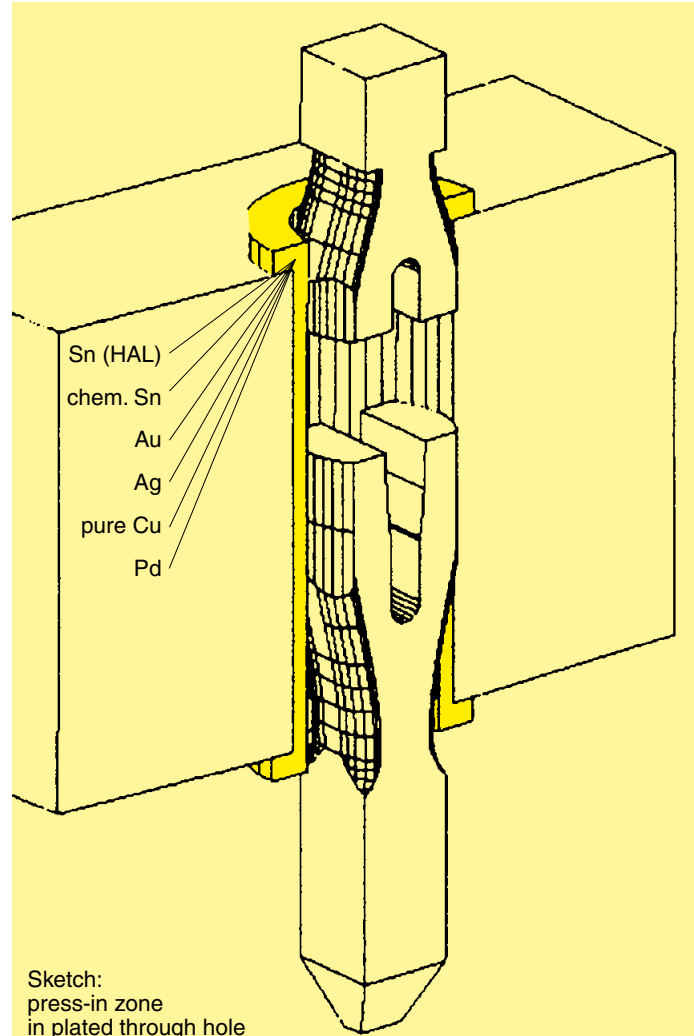
<i>Silver plated PCB</i>	Hole-Ø	1.15±0.025 mm
	Cu	min. 25 µm
	Ag	0.1-0.3 µm
	Plated hole-Ø	1.00-1.10 mm

<i>OSP copper plated PCB</i>	Hole-Ø	1.15±0.025 mm
	Cu	min. 25 µm
	Plated hole-Ø	1.00-1.10 mm

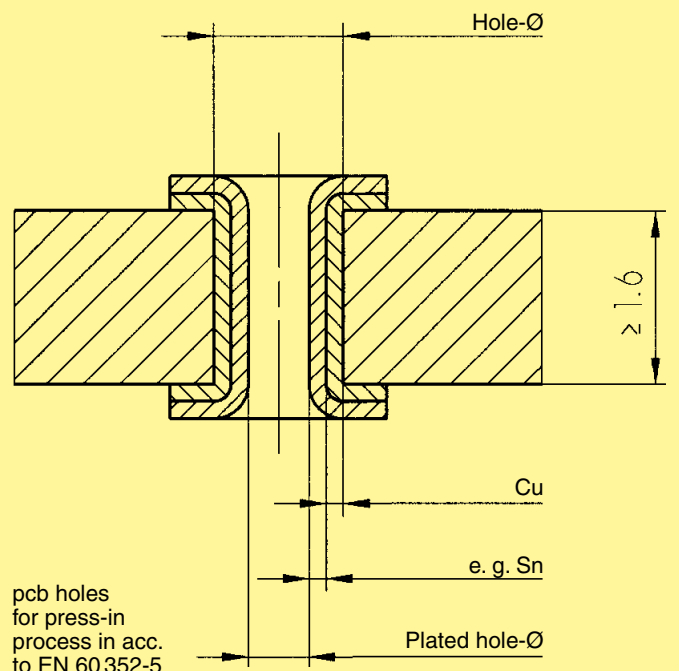
PCB board thickness: ≥ 1.6 mm



Cross section of a pcb 2.4 mm thick with various hole diameters



Sketch: press-in zone in plated through hole



pcb holes for press-in process in acc. to EN 60 352-5